

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/20/11944	
<b>1.3 Title of PCN</b>	STM32MP15x product improvement - listed products	
<b>1.4 Product Category</b>	STM32MP151x, STM32MP153x STM32MP157x	
<b>1.5 Issue date</b>	2020-02-07	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	FRANCKE CHRISTIANE
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<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	Crolles

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Revision B (cut 2.0) Limitations as described in Errata Sheet ES0438 Revision 3 - November 2019 "STM32MP151x STM32MP153x STM32MP157x" " Summary of Device errata	New Revision Z (cut 2.1): New Errata sheet ES0438 Revision 4 - January 2020 "STM32MP151x STM32MP153x STM32MP157x" " Summary of Device errata
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	Function will change only	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Correct some product functionality limitations
<b>5.2 Customer Benefit</b>	QUALITY IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability of the change is ensured by ST internal tools.
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2020-01-30
<b>7.2 Intended start of delivery</b>	2020-03-09
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	11944 MDG-MCD-RER1902 V2.0 - STM32MP15x - Die 500XXXZ - Reliability evaluation report.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2020-02-07

**9. Attachments (additional documentations)**

11944 Public product.pdf  
11944 MDG-MCD-RER1902 V2.0 - STM32MP15x - Die 500XXXZ - Reliability evaluation report.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
3051899	STM32MP151AAB3	
3051901	STM32MP151AAC3	
3051902	STM32MP151AAD3	
3051904	STM32MP153AAB3	
3051905	STM32MP153AAC3	
3051906	STM32MP153AAD3	
3018579	STM32MP157AAB3	
3018580	STM32MP157AAC3	
3018582	STM32MP157AAD3	
	STM32MP151CAB3	
	STM32MP151CAC3	
	STM32MP151CAD3	
	STM32MP153CAB3	
	STM32MP153CAC3	
	STM32MP153CAD3	
3262508	STM32MP157CAB3	
3262511	STM32MP157CAC3	
3262512	STM32MP157CAD3	

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